PIW08-CM63

MERITEK

FEATURE

- Magnetic Shield Construction for Power Circuit.
- Large Current and Low DC Resistance
- Low profile power inductors
- Application: DC/DC Converter, Battery Powered Devices,
 Low Profile High Current Power Supply, Notebook/Server
- AEC-Q200 Compliant





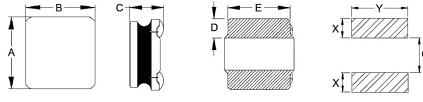
ELECTRICAL CHARACTERISTICS

Part Number	Inductance	Tolerance	Test Freq.	I _{SAT}	(A)	I _{RMS}	(A)	DCR	(mΩ)
Part Number	(µH)	(%)	(Hz)	Тур.	Max.	Тур.	Max.	Тур.	Max.
PIW08R24MCM63	0.24	±20	1V/1M	6.30	5.80	10.00	9.00	18	21.6
PIW08R33MCM63	0.33	±20	1V/1M	5.60	5.10	8.70	8.00	24	28.8
PIW08R47MCM63	0.47	±20	1V/1M	5.00	4.60	7.30	6.60	30	36
PIW08R68MCM63	0.68	±20	1V/1M	4.60	4.20	6.20	5.50	36.5	44
PIW081R0MCM63	1.00	±20	1V/1M	4.00	3.70	5.40	4.80	48	58
PIW081R5MCM63	1.50	±20	1V/1M	3.30	2.90	4.00	3.60	65	78
PIW082R2MCM63	2.20	±20	1V/1M	2.90	2.60	3.10	2.60	92	110
PIW083R3MCM63	3.30	±20	1V/1M	2.50	2.20	2.60	2.20	130	156
PIW084R7MCM63	4.70	±20	1V/1M	1.90	1.70	2.30	2.00	200	240
PIW086R8MCM63	6.80	±20	1V/1M	1.60	1.40	1.80	1.60	300	360
PIW08100MCM63	10.0	±20	1V/1M	1.20	1.10	1.40	1.20	450	540

Notes:

- 1. All test data referenced to 25°C ambient.
- 2. Saturation Current (Isat) based on inductance drop (ΔL/L0: ≦30%) approximately
- 3. Heat Rated Current (Irms) based on temperature rise (ΔT: 40 °C) approximately
- 4. Operating Temperature: -55°C ~ +125°C (Including Self-temperature rise)

DIMENSIONS



								(Unit: mm)
Part Number	Α	В	C Max	D	E	Х	Y	G
PIW08-CM63	2.5 ±0.2	2.0 ±0.2	1.2	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7

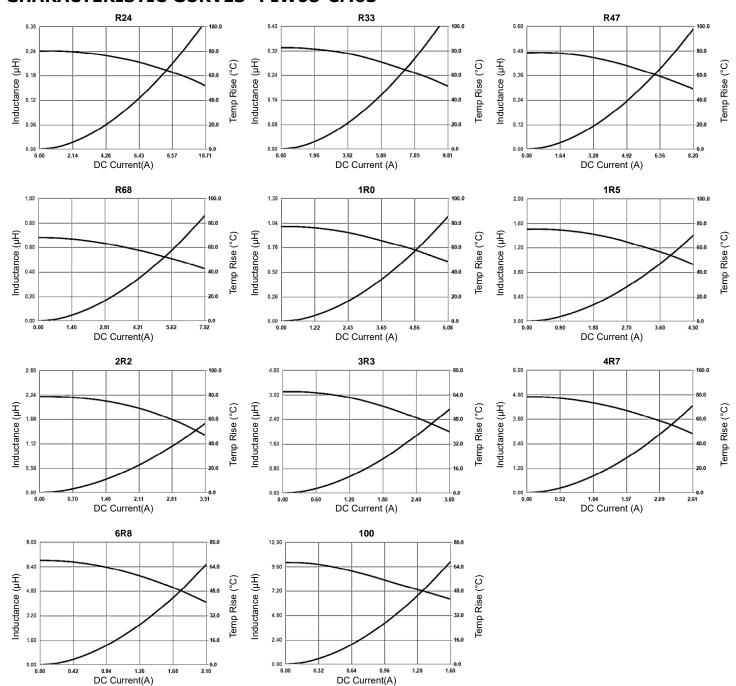
PART NUMBERING SYSTEM

 $\frac{\text{PIW}}{(1)}$ $\frac{08}{(2)}$ $\frac{100\text{M}}{(3)}$ $\frac{\text{C}}{(4)}$ $\frac{\text{M63}}{(5)}$

No	Item	Code	Description					
(1)	Product Code	PIW	Power Inductor Series, Wire Wound Type					
(2)	Size Code	08	1008, 2.5x2.0mm	L x W (mm)				
(3)	Inductance	100M	10μH ±20% (M)	R47: 0.47µH, 2R2: 2.2µH				
(4)	Internal Code	С	C: 1.2mm Height	A: 0.8mm, B: 1.0mm, D: 1.5mm				
(5)	Series Code	M63	Surface Mount Shielded, Low Profile, High Current series, AEC-Q200 Compliant					

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CHARACTERISTIC CURVES- PIW08-CM63

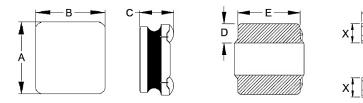




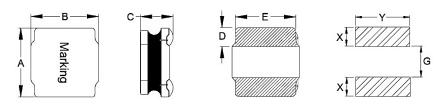
RELIABILITY TEST CONDITON AND REQUIREMENT

Item				s / Equipment		Requirement	
Inductance	HD4284A CH					Refer to specification	
DC Resistance	HP4284A, CH11025, CH3302, CH1320, CH1320S, LCR Meter CH16502, Agilent33420A Micro-Ohm Meter					Refer to specification	
DC Resistance	CH 10302, Agi					Refer to specification	
Mechanical Shock	Type SMD Lead 3 shocks in ea	Peak value (g's) 100 100 ach direction alo	Normal duration (D) (ms) 6 6 ong 3 perpendic	Wave form Half-sine Half-sine cular axes (18 s	Velocity change (Vi) ft/sec 12.3 12.3 hocks).	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	
Solderability	Test Time: 5 + Method D cate	Hrs at 155°C d 0/-0.5 seconds egory 3. (steam +0/-0.5 seconds	aging 8 hours:	C±5°C ±15min) at 260°	C±5°C	More than 95% of the terminal electrode should be covered with solder.	
Resistance to Soldering Heat	Temperature r Completely co	rature: 260±5°C ramp/immersior over the termina cles: 1 heat cyc	n and emersion ition.	s rate 25mm/s ±	6 mm/s.	Appearance: No damage Inductance: within ±10% of initial value	
Vibration	Oscillation Frequency: 10~2K~10 Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm ± 10% Testing Time: 12 hours (20 minutes, 12 cycles each of 3 orientations)					Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	
High Temperature Exposure	Temperature: Duration 1000 Measured at r		re after placing	for 24±2hrs		Appearance: No damage	
Biased Humidity	Humidity: 85±3% R.H. Temperature: 85°C±2°C Duration: 1000Hrs Min Measured at Room Temperature after placing for 24±2hrs					Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall	
High Temperature Operational Life		125±2°C OHrs Min. with ′ Room Temperat				not exceed the specification value	
Temperature Cycling	Condition for Step Temperature Duration Number of Cy Measured at r	1 -55 ±2°C 30min Min	2 125 ±2°C 1 min Max re after placing	3 125 ±2°C 30 min Min for 24±2hrs	4 Low Temp 1 min Max	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	
Thermal Shock	Condition for Step Temperature Duration Number of cyc Measured at r	1 -55 ±2°C 15±1mir	2	2 5 ±2°C 0sec 1 for 24±2 hrs.	3 125 ±2°C 15±1min	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value	
ESD	AEC-Q200-00	2 HBM ESD, C	ontact Dischar	ge Level: 4KV (Level 2)	Appearance: No damage	
Resistance to Solvents	'	wash chemical		or equivalent.		Appearance : No damage	
Terminal Strength	force 1.8kg to tested. This fo seconds. Also	tounted on a PO the side of a do rce shall be ap the force shall ot to shock the	evice being plied for 60 +1 be applied	Appearance : No damage			
Board Flex	Place the 100 fixture with the Apply a force (D) x = 2mm r	x40mm FR4 bo e component fa which will bend ninimum. Durat Force is to be a pard	cing down. the board ion: 60 (+5)	Outpool Balan C	Appearance : No damage		
Flammability	Electrical Test	not Required				V-0 or V-1 are acceptable.	

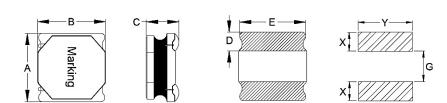
DIMENSIONS



				200				(Unit: mm)
Part Number	Α	В	C Max	D	E	Х	Y	G
PIW06-BM63	2.0 ±0.2	1.6 ±0.2	1.0	0.7 ±0.3	1.6 ±0.2	1.0	2.0	0.5
PIW06-CM63	2.0 ±0.2	1.6 ±0.2	1.2	0.7 ±0.3	1.6 ±0.2	1.0	2.0	0.5
PIW08-BM63	2.5 ±0.2	2.0 ±0.2	1.0	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7
PIW08-CM63	2.5 ±0.2	2.0 ±0.2	1.2	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7



Part Number	Α	В	C Max	D	E	X	Y	G
PIW-30CM63	3.0±0.2	3.0±0.2	1.2	0.9 ±0.3	2.7 ±0.3	1.3	3.5	0.9
PIW-30DM63	3.0±0.2	3.0±0.2	1.5	0.9 ±0.3	2.7 ±0.3	1.3	3.5	0.9



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Part Number	Α	В	C Max	D	E	Х	Υ	G	
PIW-40EM63	4.0±0.2	4.0±0.2	2.0	1.1 ±0.3	3.5 ±0.3	1.5	4.5	1.5	



RECOMMENDED SOLDERING PROFILES

	Reflow Condition	
_	Temp. Min T _{s(min)}	150°C
Pre Heat	Temp. Max T _{s(max)}	200°C
11001	Time (min. to max.) (t _s)	60 ~120 seconds
	ramp up rate (Liquidus ture) (T∟) to peak	3°C/second max
T _{S(max)} to	T∟(Ramp-up rate)	3°C/second max
Reflow	Temp. (T _L)	217°C
Reliow	Time (min. to max.) (t _L)	60 ~150 seconds
Peak Ten	nperature (T _P)	See table below
Time with	nin 5°C of actual peak ture (t _p)	10 seconds max
Ramp-do	wn Rate	6°C/second max
Reflow T	imes	3 times max

Peak Temperature (T _P)							
Volume	< 350mm ³	350-2000mm ³	> 2000mm ³				
Thickness < 1.6mm	260°C	260°C	260°C				
Thickness 1.6-2.5mm	260°C	250°C	245°C				
Thickness ≥ 2.5mm	250°C	245°C	245°C				

^{*}Specifications subject to change without notice

